





AMENDMENT UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE GROUP 1775 PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of .

Docket No: Q67726

Mitsuo OSADA, et al.

Appln. No.: 10/009,822

Group Art Unit: 1775

Confirmation No.: 6202

Examiner: Michael E. Lavilla

Filed: December 13, 2001

For MATERIAL FOR A HEAT DISSIPATION SUBSTRATE FOR MOUNTING A

SEMICONDUCTOR, METHOD OF PRODUCING THE SAME, AND CERAMIC

PACKAGE USING THE SAME

AMENDMENT UNDER 37 C.F.R. § 1.116

MAIL STOP AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated March 29, 2005, please amend the aboveidentified application as follows on the accompanying pages.